

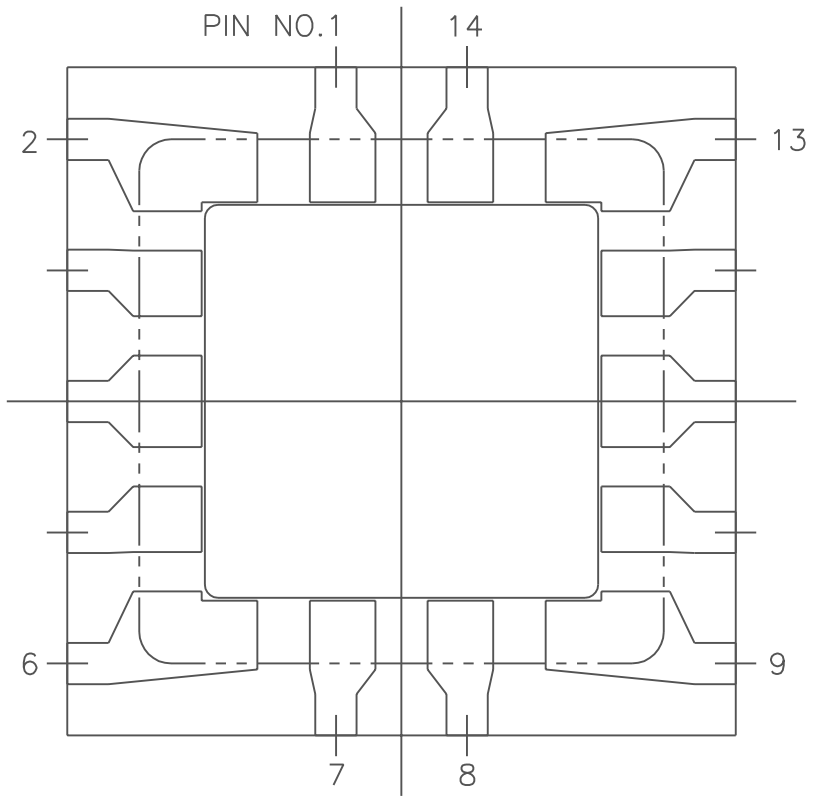
WIRE BOND PAD/CONNECTOR PIN INTERCONNECTION PLAN

W/B NO.	PIN NO.
1	1
2	2
3	3
4	4
5	5
6	6
7	7
8	8
9	9
10	10
11	11
12	12
13	13
14	14

D/A NO.	PIN NO.
A	1
B	7
C	8
D	14

MODIFICATION						NAME	14 LEAD FLAT PACKAGE	TOLERANCE	UNLESS OTHERWISE SPECIFIED	DRAWN	Y.T	CHECKED	H.TA/S.NI	APPROVED	H.SA	DATE	APR.17.'00
						SCALE	20 / 1	MATERIAL									
									THIRD ANGLE PROJECTION								
		CHANGED	DATE	DRAWN	CHECKED	APPROVED		KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO.	KD-FA0479		SHEET	2 / 4				

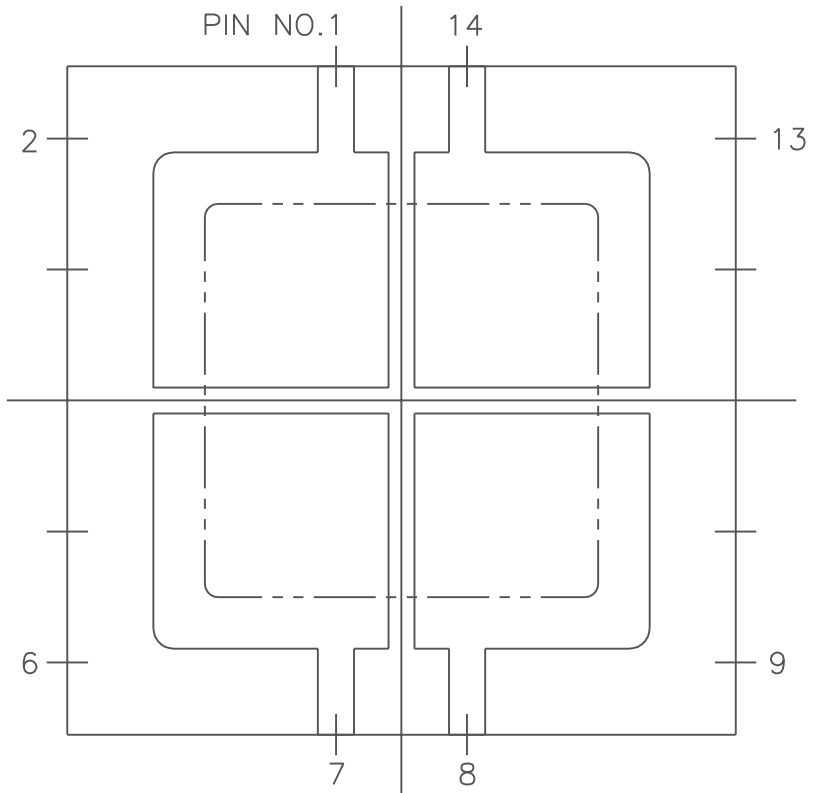




MP-2

MODIFICATION						NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
						14 LEAD FLAT PACKAGE	UNLESS OTHERWISE SPECIFIED	Y.T	H.TA/S.NI	H.SA	APR.17.'00
						SCALE 20 / 1	MATERIAL				
								THIRD ANGLE PROJECTION			
	CHANGED	DATE	DRAWN	CHECKED	APPROVED	KYOCERA	KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO.			SHEET
								KD-FA0479			3 / 4





MP-3

MODIFICATION						NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
						14 LEAD FLAT PACKAGE	UNLESS OTHERWISE SPECIFIED	Y.T	H.TA/S.NI	H.SA	APR.17.'00
						SCALE 20 / 1	MATERIAL				
							THIRD ANGLE PROJECTION				
	CHANGED	DATE	DRAWN	CHECKED	APPROVED	KYOCERA	KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO.		SHEET	
								KD-FA0479		4 / 4	

